

TECHNICAL SPECIFICATION FOR PROCUREMENT OF "EPOXY RESIN SYSTEM"

Sl. No.	Description	Specification
1	Epoxy Resin System	Bisphenol-A based, filled, Flexibilized, Accelerator added, Solvent free, Hot curing castable "Epoxy Resin system"-Pasty, prefilled, hot-curing, single component epoxy casting system with excellent thermal conductivity
2	VISCOSITY@50 Deg. C (m. PaS)	5,000 - 20,000
3	Specific gravity/ Density of Epoxy Resin @25 Deg. C (g/cc)	2.2-2.6
4	Thermal conductivity	2.9-3.5 W/m. K
General Specifications		
1	Suitability	Technical suitability of the offered "Epoxy Resin Hardener System" for APG (Automatic Pressure Gelation) Process and or 'Vacuum Casting Process' or similar process/es are desired and the same to be certified by the Vendor.
2	Product Properties	Casting of High Voltage Insulation Products to obtain Electrical Breakdown Strength (BDV) in the range of 18 -25 kV/mm, Volume Resistivity in the range of 1×10^{-12} - 1×10^{-15} and Glass Transition Temperature in the range of 110-125 Deg. C. Technical-suitability of the System for such High Voltage Insulation Applications is to be endorsed by the Vendor for obtaining defect-free cured products.
3	Warranty	All supplied items to be provided with warranty for 12 months from date of dispatch.
4	Manufactures Test Certificate	Manufacturer's Test Certificate required and shall be provided before dispatch.

 13/03/2024

 13/3/24